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SPECIFICATION AND PERFORMANCE

SERIES:
115B Series
FILE:
115B Series_spec
DATE:
2012/12/12

Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 115B Series.

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIAL AND FINISH		
INSULATOR	**Material**	Housing: LCP UL94V-0. Black Cover: LCP UL94V-0. Black
CONTACT	**Material**	Contact: phosphor bronze C5191
	Plating	Gold plating on contact area, nickel under plating overall.
SHELL OR COVER	**Material**	
	Plating	
RATING	Current Rating: 0.5A per pin Voltage Rating: 30V DC/AC Operating Temperature: -40℃ to +85℃ Storage Temperature: -40℃ to +85℃	

ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	Initial: 30 mΩ Maximum After test: 30 mΩ Maximum	(EIA 364-23) Subject mated contacts assembled in housing to 20mV maximum open circuit at 100 mA maximum The object of this test is to detail a standard method to measure the electrical resistance across a pair of mated contacts such that the insulating films, if present will not be broken or asperity melting will not occur.
Insulation Resistance	Insulation Resistance: 1000MΩMin	(EIA 364-21) Apply a 500V DC between adjacent terminals and between terminals to ground
Dielectric Withstanding Voltage	No flashover or insulation breakdown	(EIA 364-20) Apply a voltage 500V AC R.M.S for 1 minute between adjacent terminals and between terminals to ground

MECHANICAL

Item	Requirement	Test Condition
Durability	No physical damage.	(EIA 364-09) Insertion and extraction are repeated 5000 cycles with the actually card at the speed rate of 700 min cycles/hour. Exchange the actually card every 2000cycles.

Vibration	No Damage Contact Resistance: 30milliohms MAX Change from initial: 30milliohms Discontinuity: 1microsecond Max.	(EIA-364-28) Amplitude:1.52mm P-P or 1.47mm/s^2 Sweep time:10~55~10Hz in 20 minutes Duration:12 time in each (total of 36 times) Electrical: DC 100 mA current Load shall be flowed during the test

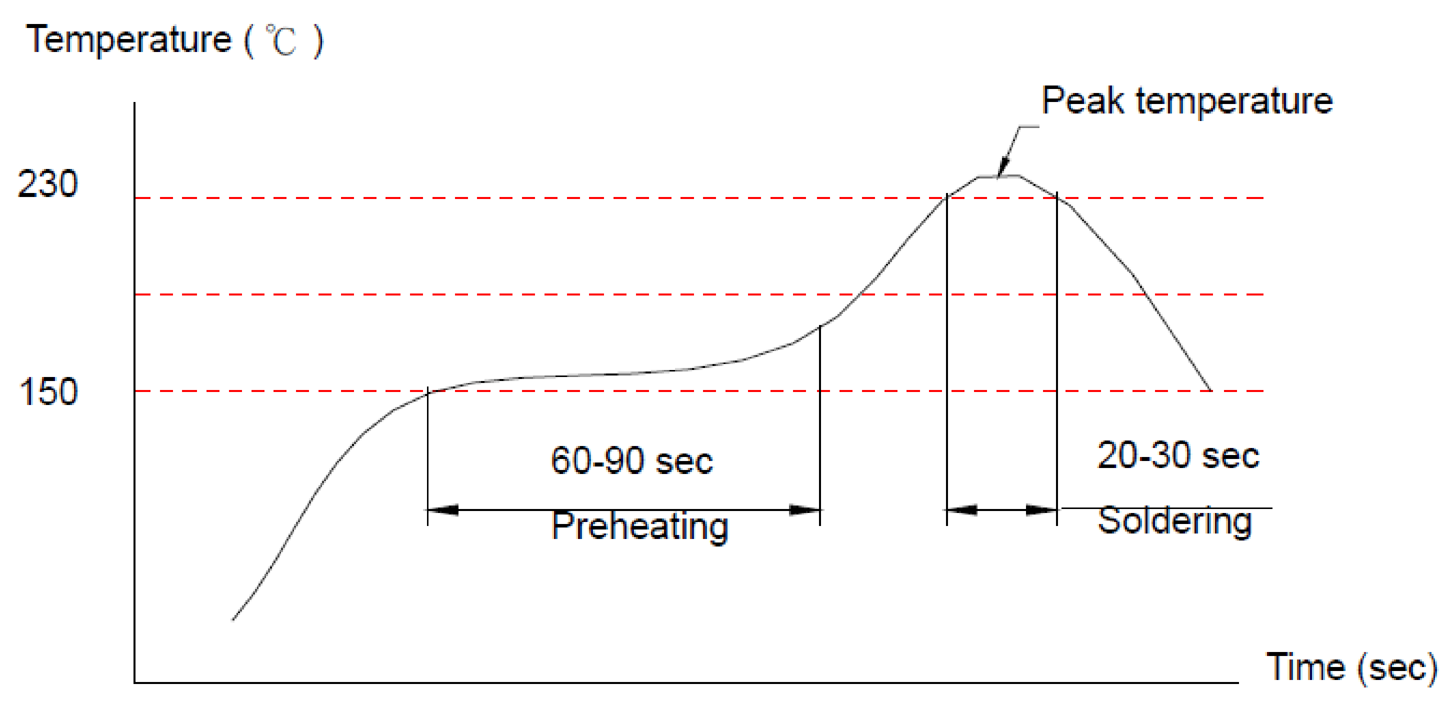
ENVIRONMENTAL

Item	**Requirement**	**Test Condition**
Thermal Shock	No evidence of damage.	(EIA 364-32 I) Subject mated connectors should be tested according to the condition listed below: Temperature: -25 ~ 85℃ Cycles: 5 cycles Exposure time at temp. 30 minutes.
Humidity	No appearance damaged	(EIA 364-31) Mate a dummy card and expose to 60±2℃ for 96 hours Relative humidity 90. Upon completion of the exposure period, the test specimens shall be conditioned at anibient room conditions for 1 to 2hours,after which the specified measurements shall be performed

Heat Resistance	No appearance damaged	(EIA 364-17) Mate a dummy card and expose to 70±2℃ for 96Hr Upon completion of the exposure period,the test specimens shall be conditioned at ambient room conditions for 1 to 2Hr,after which the specified measurements shall be performed.

SOLDER ABILITY

Item	Requirement	Test Condition
Solderability	The surface of the portion to be soldered shall at least 95% covered	(EIA 364-52) After one hour steam aging. The object of test procedure is to detail a unfirm test methods for determining sim card connector solderability. The test procedure contained here utilizes the solder dip technique. It is not intended to test or evaluate solder cup, solder eyelet, other hand-soldered type or SMT type terminations.
Resistance to Soldering Heat	260℃±5℃ 10Sec	Peak temperature: 260℃±5℃ 10Sec Soldering temperature: 230℃ Preheating temperature: 150~180℃


Temperature (℃)
Peak temperature
230
150
60-90 sec
Preheating
20-30 sec
Soldering
Time (sec)